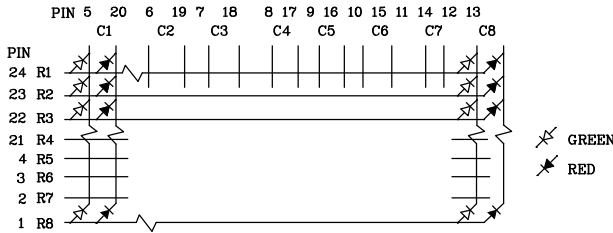
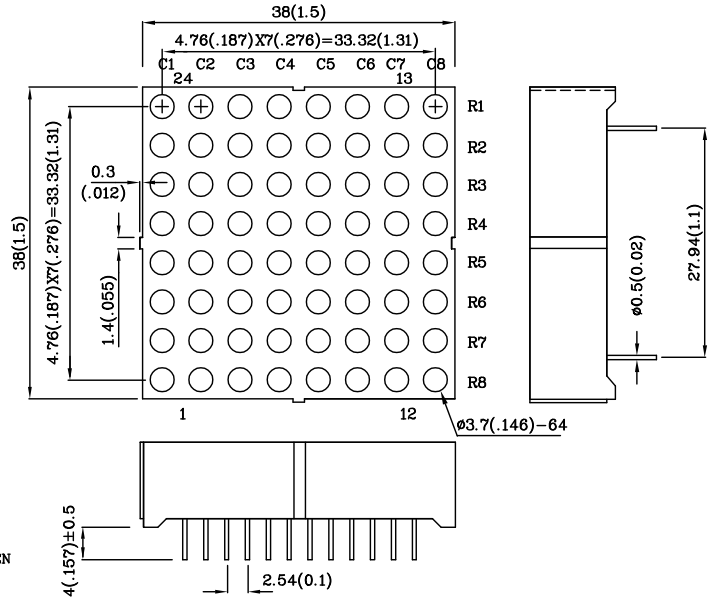


Features

- 1.5 INCH MATRIX HEIGHT.
- DOT SIZE 3.7mm.
- LOW CURRENT OPERATION.
- HIGH CONTRAST AND LIGHT OUTPUT.
- COMPATIBLE WITH ASCII AND EBCDIC CODES.
- STACKABLE HORIZONTALLY AND VERTICALLY.
- COLUMN CATHODE AVAILABLE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- MULTICOLOR AVAILABLE.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE DOT.
- RoHS COMPLIANT.



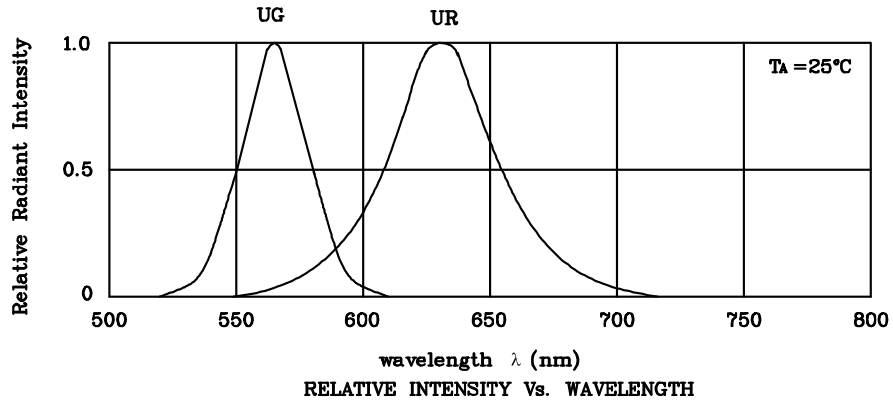
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.25(0.01") unless otherwise noted.

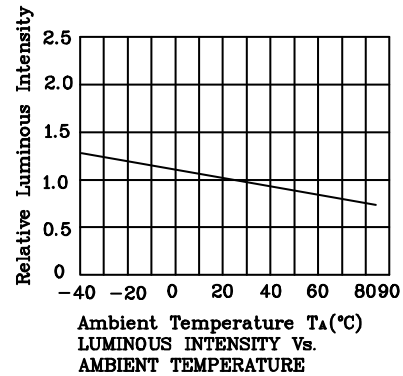
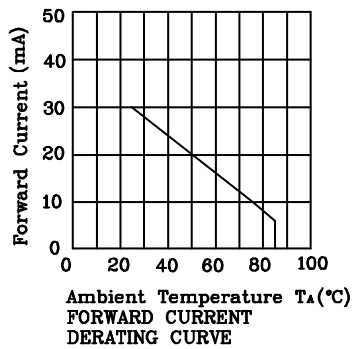
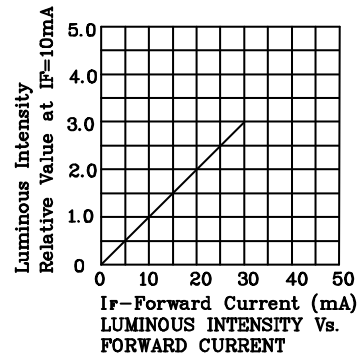
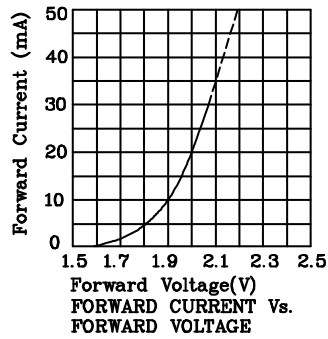
Absolute maximum ratings (TA=25°C)		UR (GaAsP/ GaP)	UG (GaP)	Unit
Reverse Voltage	VR	5	5	V
Forward Current	IF	30	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	160	140	mA
Power Dissipation	PT	105	105	mW
Operating Temperature	TA	-40 ~ +85		°C
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 5 Seconds			

Operating Characteristics (TA=25°C)		UR (GaAsP/ GaP)	UG (GaP)	Unit
Forward Voltage (Typ.) (IF=10mA)	VF	1.9	2.0	V
Forward Voltage (Max.) (IF=10mA)	VF	2.5	2.5	V
Reverse Current (VR=5V)	IR	10	10	uA
Wavelength of Peak Emission (IF=10mA)	λ p	627	565	nm
Wavelength of Dominant Emission (IF=10mA)	λ D	625	568	nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	Δλ	45	30	nm
Capacitance (VF=0V, f=1MHz)	C	15	15	pF

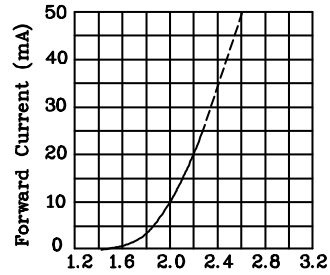
Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd	Wavelength nm λ P	Description
XMURG38C8	Red	GaAsP/GaP	min. 1900	typ. 10490	Column Cathode
	Green	GaP	3000	15990	



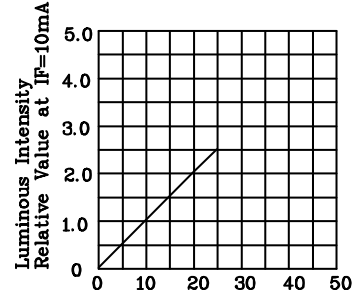
❖ UR



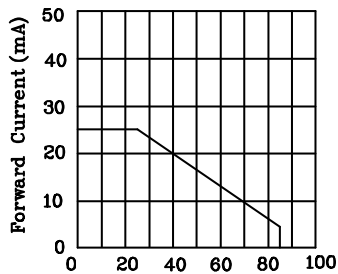
❖ UG



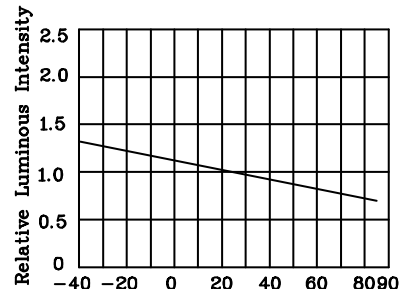
Forward Voltage(V)
 FORWARD CURRENT Vs.
 FORWARD VOLTAGE



If-Forward Current (mA)
 LUMINOUS INTENSITY Vs.
 FORWARD CURRENT

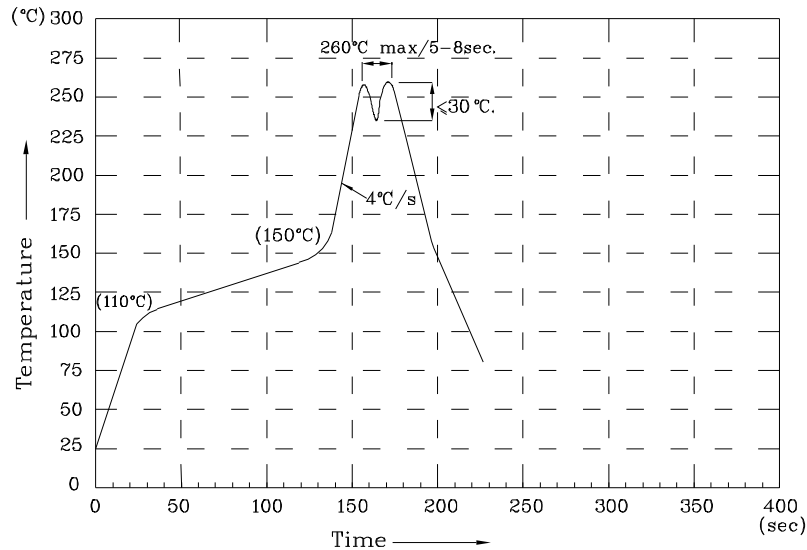


Ambient Temperature TA(°C)
 FORWARD CURRENT
 DERATING CURVE



Ambient Temperature TA(°C)
 LUMINOUS INTENSITY Vs.
 AMBIENT TEMPERATURE

Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.